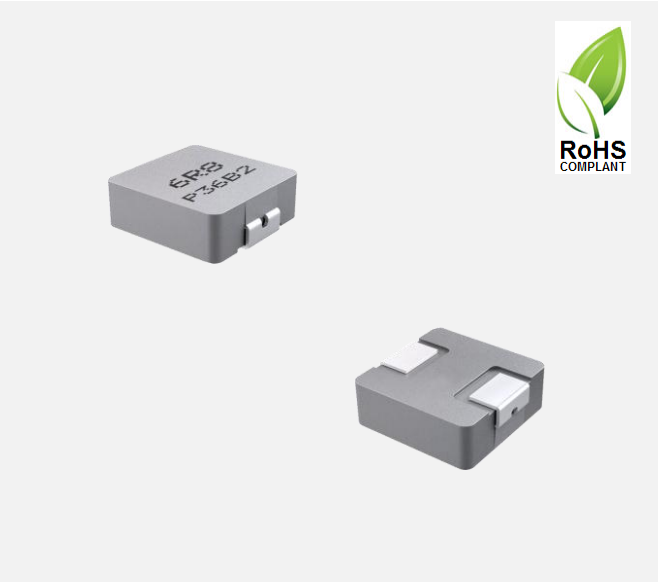
CODACA科达嘉

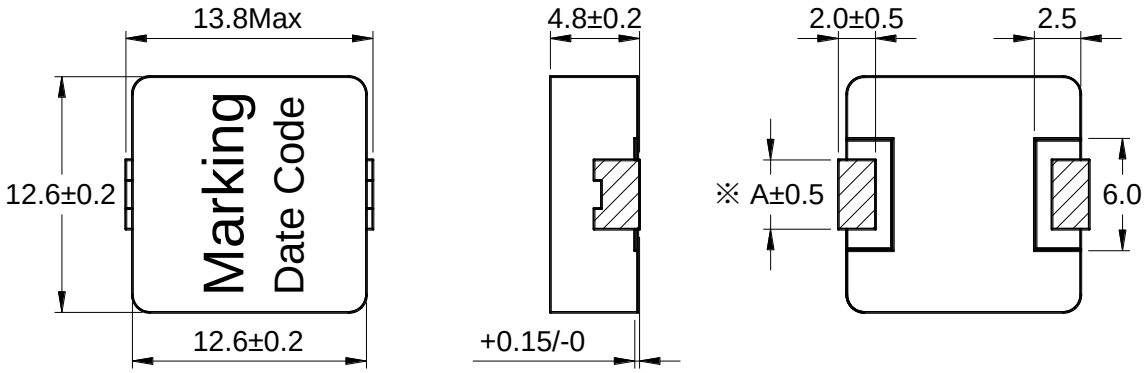
Molding Power Choke
- CSAB1250A Series



Outline:
产品概要

- Magnetic shielded structure: excellent resistance to electro magnetic interference(EMI).
  磁屏蔽结构：抗电磁干扰(EMI)性能强。
- A composite structure, ultra low buzz noise.
  一体成型结构，超低蜂鸣噪音。
- Low loss, high efficiency, wide application frequency.
  低损耗，高效率，应用频率宽。
- Lightweight design, save space, suitable for high density SMT.
  轻薄型设计，节省空间，适合高密度贴装。
- Die-casting by low loss alloy powder: low impedance, small parasitic capacitance.
  低损耗合金粉末压铸：低阻抗，寄生电容小。
- Operating temperature : -40℃ ～ +125℃ (Including coil's temperature rise)
  工作温度：-40℃ ～ +125℃ (包含线圈发热)

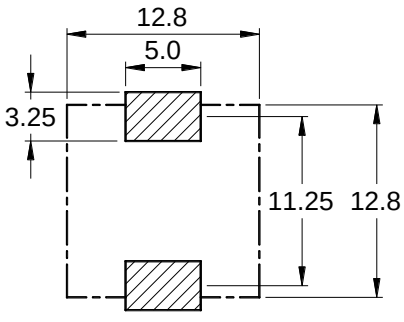
1 Appearance and dimensions (mm)
外形尺寸



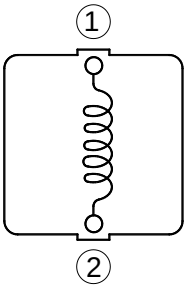
Part No.	R68, 1R5, 3R3	Others
Dimension A	3.00	3.70

2 Marking
印字标识

3 Reference land pattern (mm)
参考基板尺寸



4 Schematic
原理图



5 Electrical characteristics
电气特性

Part No. 型 号	Inductance (μH) 电感值 ※1 ±20%	D.C.R. (mΩ) 直流电阻 Typical	 Max	Saturation current (A) 饱和电流 ※2 Typical	Temperature rise current (A) 温升电流 ※3 Typical
CSAB1250A-R15M	0.15	0.50	0.60	75.0	50.0
CSAB1250A-R22M	0.22	0.50	0.80	70.0	50.0
CSAB1250A-R33M	0.33	0.75	1.00	60.0	41.0
CSAB1250A-R47M	0.47	1.05	1.20	50.0	35.0
CSAB1250A-R68M	0.68	1.60	1.90	40.0	28.5
CSAB1250A-R80M	0.80	1.80	2.00	40.0	26.5
CSAB1250A-1R0M	1.00	1.95	2.20	37.0	25.5
CSAB1250A-1R5M	1.50	2.60	3.20	33.0	22.0
CSAB1250A-2R2M	2.20	4.40	5.00	32.0	17.0
CSAB1250A-3R3M	3.30	5.30	7.00	22.0	15.5
CSAB1250A-4R7M	4.70	9.80	15.0	18.0	11.4
CSAB1250A-5R6M	5.60	12.1	17.0	17.0	10.2
CSAB1250A-6R8M	6.80	16.3	20.0	15.0	8.80
CSAB1250A-8R2M	8.20	19.1	21.0	13.0	8.10
CSAB1250A-100M	10.0	20.5	22.0	12.0	7.80
CSAB1250A-150M	15.0	32.5	40.0	10.0	6.20
CSAB1250A-220M	22.0	42.0	58.0	6.50	5.50
CSAB1250A-330M	33.0	62.1	84.0	6.00	4.50
CSAB1250A-470M	47.0	96.8	130	5.00	3.60

■ All data is tested based on 25℃ ambient temperature.
所有数据基于环境温度 25℃条件下测试。

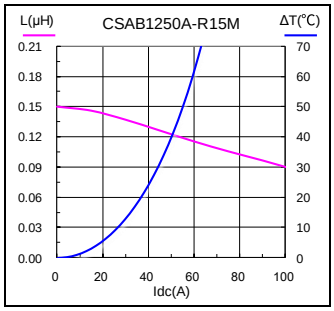
※1 Inductance measure condition at 100kHz, 1V.
电感测试条件为 100kHz, 1V。

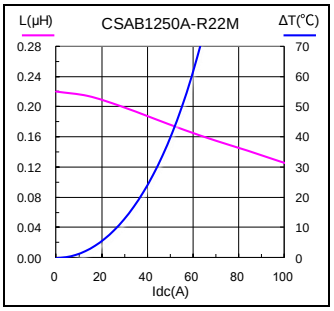
※2 Saturation current：the actual value of DC current when the inductance decrease 30% of its initial value.
饱和电流：电感值下降其初始值的 30%时所加载的实际直流电流值。

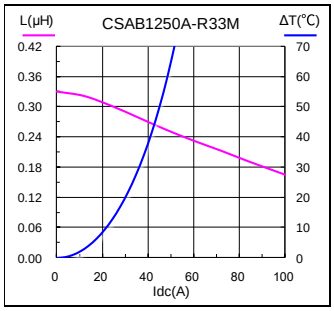
※3 Temperature rise current：the actual value of DC current when the temperature rise is ΔT40℃(Ta=25℃).
温升电流：使产品温度上升到 ΔT40℃时所加载的实际直流电流值(Ta=25℃)。

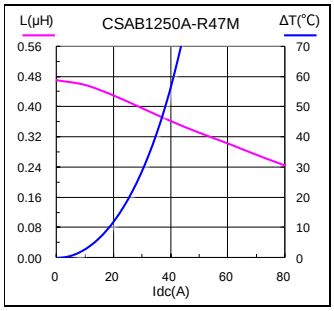
※ Special remind：Circuit design, component placement, PWB size and thickness, cooling system and etc. all will affect the product temperature. Please verify the product temperature in the final application.
特别提醒：线路设计，组件布局，印刷线路板(PWB)尺寸及厚度，散热系统等均会影响产品温度。
请务必在最终应用时，验证产品发热状况。

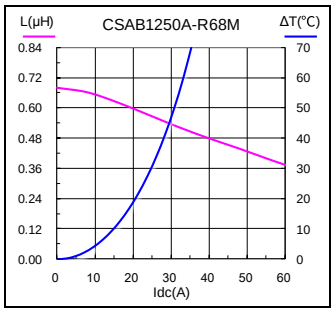
6 Saturation current VS temperature rise current curve
饱和电流 VS 温升电流曲线

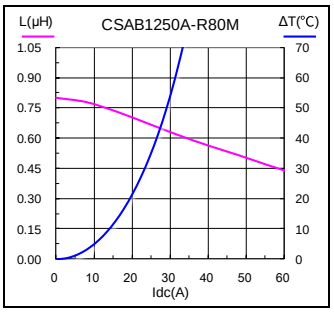


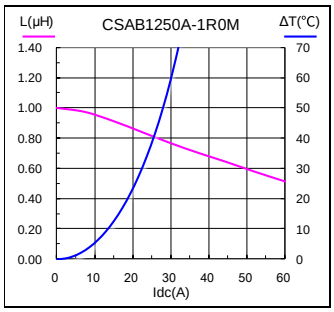


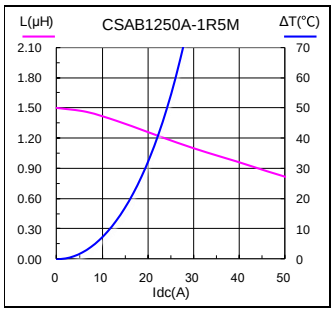


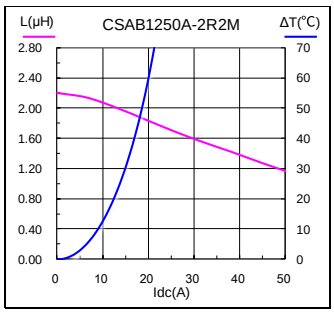


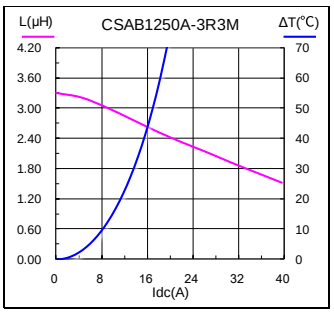


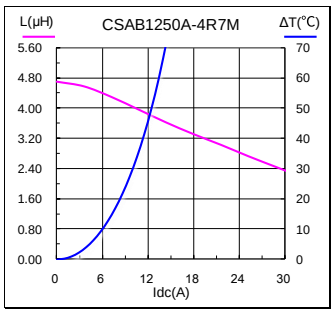


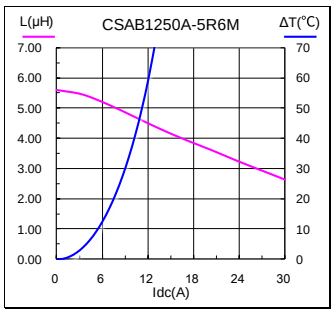


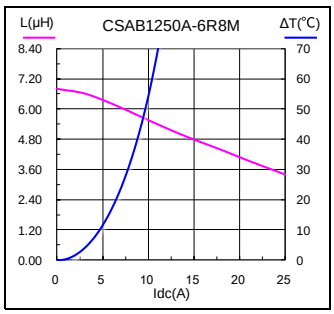


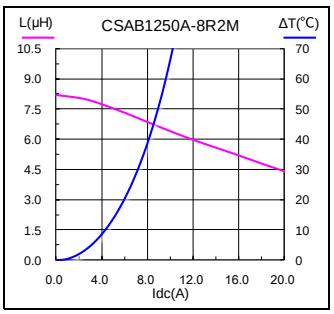


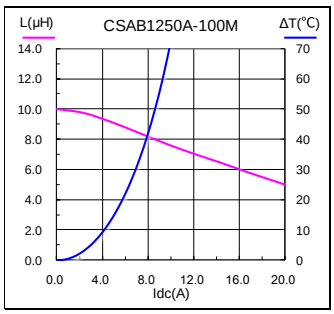


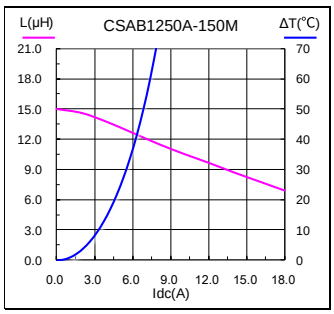


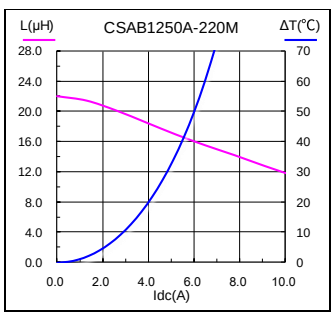


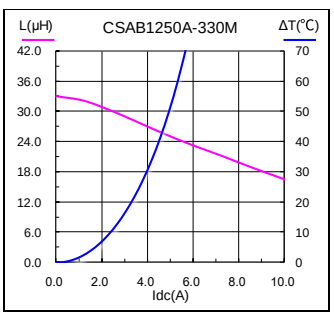


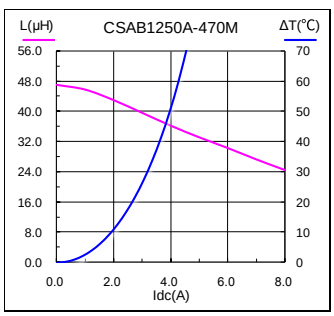






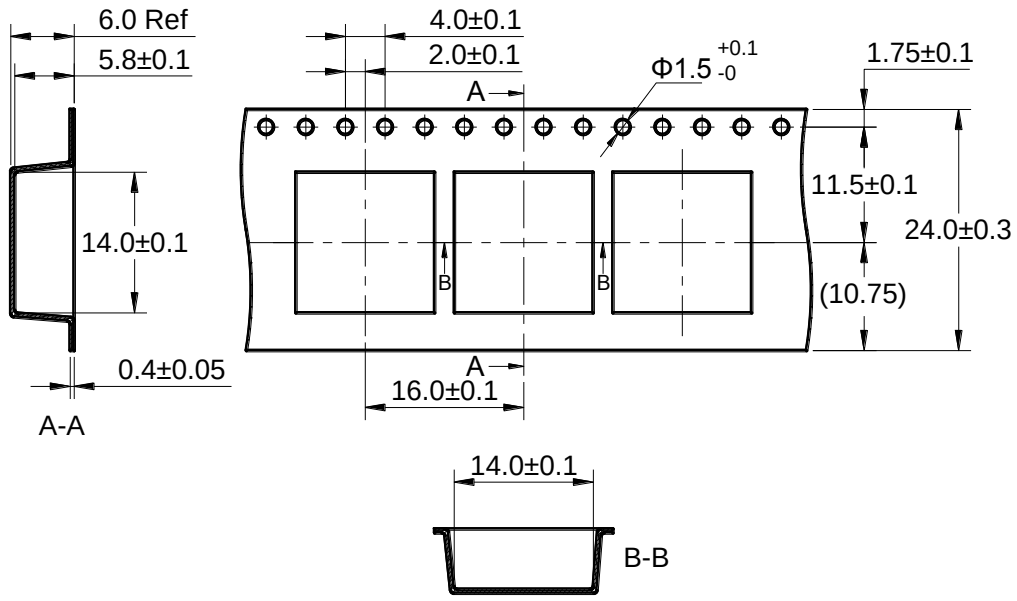






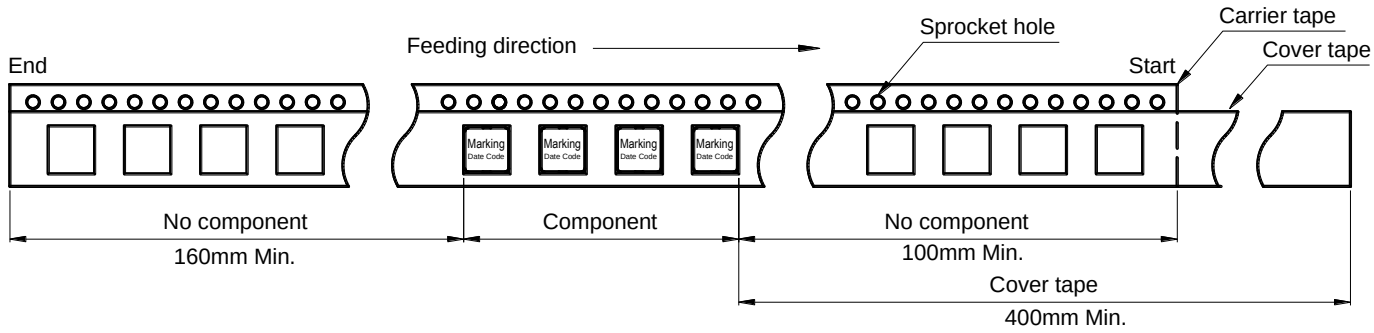
7 Packing specification
包装规格

7.1 Carrier tape dimensions (mm)
载带尺寸



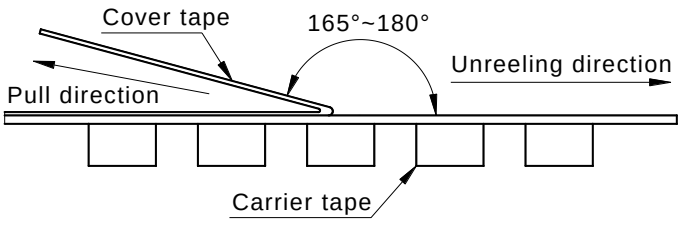
※ Packing is referred to the international standard IEC 60286-3.
包装参照国际标准 IEC 60286-3。

7.2 Tape direction
捆包方向

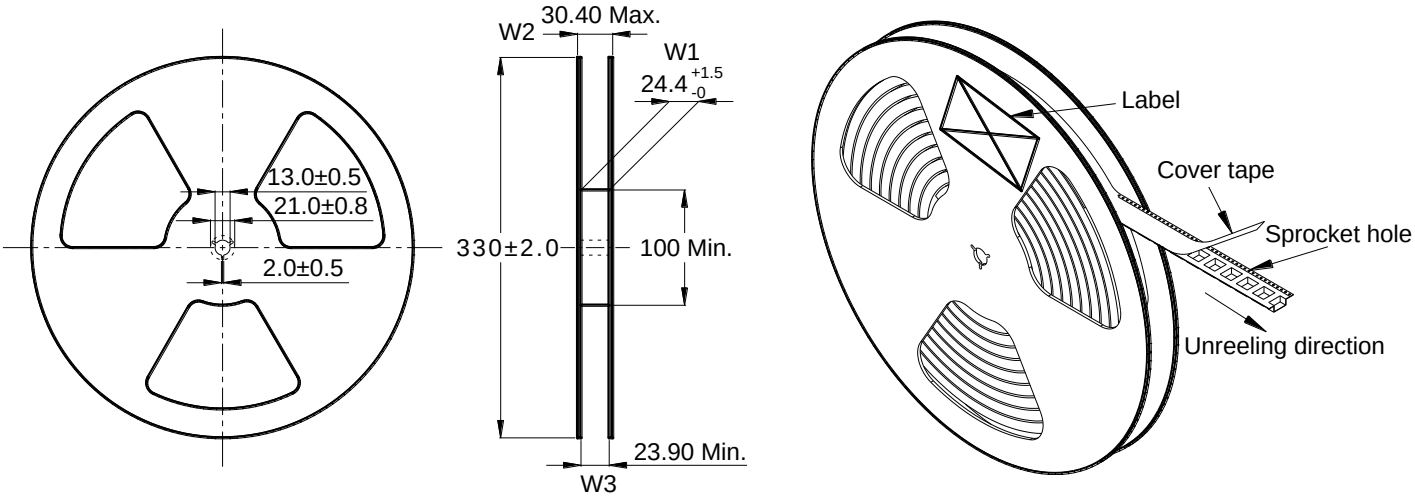


7.3 Cover tape peel off condition
盖带剥离条件

- Cover tape peel force shall be 0.1 to 1.3N.
  盖带剥离力度为 0.1～1.3N。
- Reference peel speed 300±10mm/min.
  参考剥离速度 300±10mm/分钟。



7.4 Reel dimensions (mm)
卷盘尺寸



7.5 Carton dimensions and packing quantity
包装箱尺寸和包装数量

■ Inner Carton：340×340×95mm
内包装盒

■ Out Carton ： 355×355×385mm
外包装箱

Product Series 产品系列	Quantity / Reel 数量 / 卷	Inner Carton Quantity 内盒 包装数量	Out Carton Quantity 外箱 包装总数量
CSAB1250A	500pcs	(500×2) = 1000pcs	(1000×3) = 3000pcs

7.6 Label making
标签标识

The following items will be marked on the reel of product label and shipping label.
以下项目将明确标识于产品卷盘标签以及运输标签上。

Production Label
产品标签

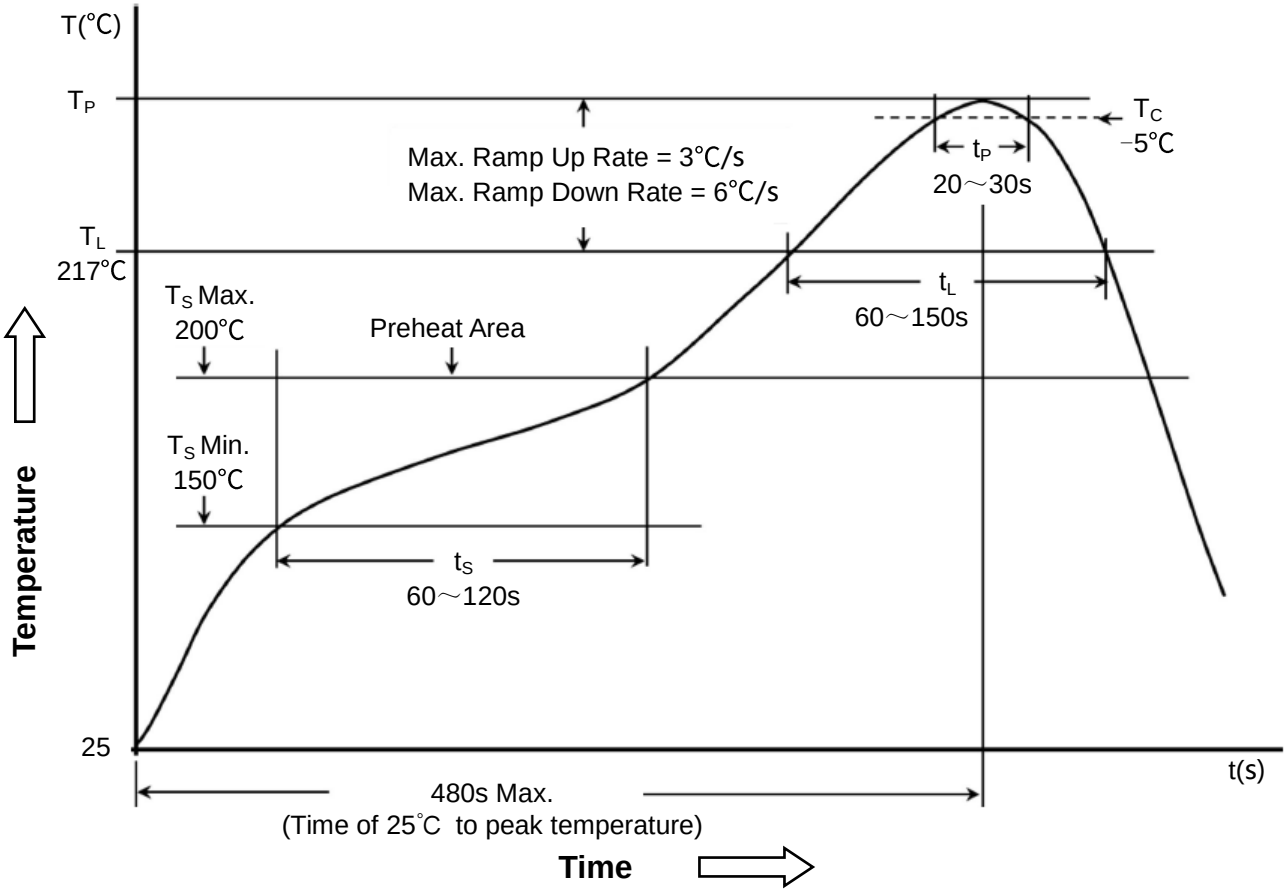
■ Part No.
产品型号
■ Electrical Information
产品电性信息
■ Quantity
数 量
■ Packing No.
包装流水号

Shipping Label
运输标签

■ Customer Name
客户名称
■ Customer Part No.
客户型号
■ Supplier Part No.
供应商型号
■ Supplier Name
供应商名称
■ Country of origin
产品产地

8 Soldering specification
焊接规格

8.1 Reflow profile for SMT components
SMT 回流焊温度曲线



8.2 Classification of peak package body temperature (T_P)
封装体峰值温度(T_P)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm^3	350～2000 mm^3	>2000 mm^3
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6～2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.
回流焊参照标准 IPC/JEDEC J-STD-020D。